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Advanced Micro- and Nano-Manufacturing Technologies

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Message from the Guest Editor

One of the major issues of HEAM in recent decades is the development of advanced materials manufacturing using its advantages to expand their scientific technologies and industrial applications. It needs tremendous dedicated works on applied AM processes, deposition methodologies, post-processing technologies, assisted numerical simulation and analyses, which significantly affects the HEAM part quality. The HEAM of advanced materials will push the materials wheels of the high performance and functionality for the worldwide technologies.

This special Issue would focus on recent works related to high energy additive manufacturing technologies on advanced materials. Topics can include but are not limited to:

1. High energy additive manufacturing processes using advanced materials;
2. Post-processing technology of HEAM parts (including heat treatment, surface and shape modification, etc.);
3. Functional/graded materials using HEAM methodologies;
4. Modeling and numerical analyses in additive manufacturing processes;
5. High-throughput materials design and intelligent control for additive manufacturing;
6. Microstructure, phase transformation and mechanical properties of the AM parts.





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Message from the Editor-in-Chief

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